

NUP1301ML3T1

Low Capacitance Diode Array for ESD Protection in a Single Data Line

NUP1301ML3T1 is a MicroIntegration™ device designed to provide protection for sensitive components from possible harmful electrical transients; for example, ESD (electrostatic discharge).

Features

- Low Capacitance (0.9 pF Maximum)
- Single Package Integration Design
- Provides ESD Protection for JEDEC Standards JESD22
 - Machine Model = Class C
 - Human Body Model = Class 3B
- Protection for IEC61000–4–2 (Level 4)
 - 8.0 kV (Contact)
 - 15 kV (Air)
- Ensures Data Line Speed and Integrity
- Fewer Components and Less Board Space
- Direct the Transient to Either Positive Side or to the Ground
- Pb–Free Package is Available

Applications

- T1/E1 Secondary IC Protection
- T3/E3 Secondary IC Protection
- HDSL, IDSL Secondary IC Protection
- Video Line Protection
- Microcontroller Input Protection
- Base Stations
- I²C Bus Protection

MAXIMUM RATINGS (Each Diode) (T_J = 25°C unless otherwise noted)

| Rating | Symbol | Value | Unit |
|--|------------------------|-------------------|------|
| Reverse Voltage | V _R | 70 | Vdc |
| Forward Current | I _F | 215 | mAdc |
| Peak Forward Surge Current | I _{FM(surge)} | 500 | mAdc |
| Repetitive Peak Reverse Voltage | V _{RRM} | 70 | V |
| Average Rectified Forward Current (Note 1) (averaged over any 20 ms period) | I _{F(AV)} | 715 | mA |
| Repetitive Peak Forward Current | I _{FRM} | 450 | mA |
| Non–Repetitive Peak Forward Current t = 1.0 μs t = 1.0 ms t = 1.0 S | I _{FSM} | 2.0 1.0 0.5 | A |

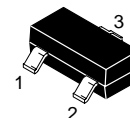
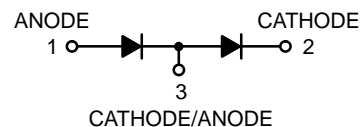
Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

1. FR–5 = 1.0 × 0.75 × 0.062 in.



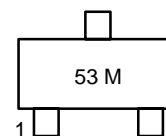
ON Semiconductor®

<http://onsemi.com>



SOT–23
CASE 318
STYLE 11

MARKING DIAGRAM



53 = Device Code
M = Date Code

ORDERING INFORMATION

| Device | Package | Shipping† |
|---------------|---------------------|--------------------|
| NUP1301ML3T1 | SOT–23 | 3000 / Tape & Reel |
| NUP1301ML3T1G | SOT–23 (Pb–Free) | 3000 / Tape & Reel |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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THERMAL CHARACTERISTICS

| Characteristic | Symbol | Max | Unit |
|--|-----------------|-------------|-----------------------------|
| Thermal Resistance Junction-to-Ambient | $R_{\theta JA}$ | 625 | $^{\circ}\text{C}/\text{W}$ |
| Lead Solder Temperature Maximum 10 Seconds Duration | T_L | 260 | $^{\circ}\text{C}$ |
| Junction Temperature | T_J | -65 to 150 | $^{\circ}\text{C}$ |
| Storage Temperature | T_{stg} | -65 to +150 | $^{\circ}\text{C}$ |

ELECTRICAL CHARACTERISTICS ($T_J = 25^{\circ}\text{C}$ unless otherwise noted) (Each Diode)

| Characteristic | Symbol | Min | Typ | Max | Unit |
|----------------|--------|-----|-----|-----|------|
|----------------|--------|-----|-----|-----|------|

OFF CHARACTERISTICS

| | | | | | |
|---|------------|----|---|----------------------------|------------------|
| Reverse Breakdown Voltage ($I_{(BR)} = 100 \mu\text{A}$) | $V_{(BR)}$ | 70 | - | - | Vdc |
| Reverse Voltage Leakage Current ($V_R = 70 \text{ Vdc}$) ($V_R = 25 \text{ Vdc}$, $T_J = 150^{\circ}\text{C}$) ($V_R = 70 \text{ Vdc}$, $T_J = 150^{\circ}\text{C}$) | I_R | - | - | 2.5 30 50 | μAdc |
| Diode Capacitance (between I/O and ground) ($V_R = 0$, $f = 1.0 \text{ MHz}$) | C_D | - | - | 0.9 | pF |
| Forward Voltage ($I_F = 1.0 \text{ mAdc}$) ($I_F = 10 \text{ mAdc}$) ($I_F = 50 \text{ mAdc}$) ($I_F = 150 \text{ mAdc}$) | V_F | - | - | 715 855 1000 1250 | mV_{dc} |

- FR-5 = $1.0 \times 0.75 \times 0.062$ in.
- Alumina = $0.4 \times 0.3 \times 0.024$ in, 99.5% alumina.

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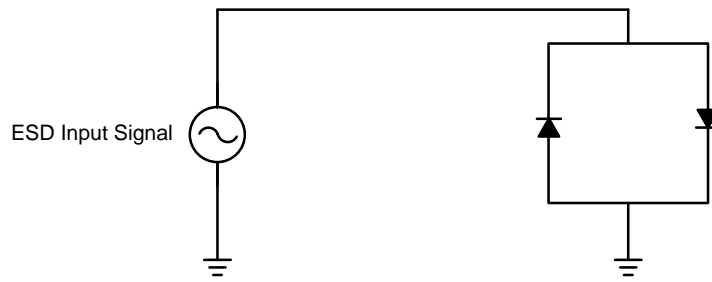


Figure 1. ESD Test Circuit

APPLICATION NOTE

Electrostatic Discharge

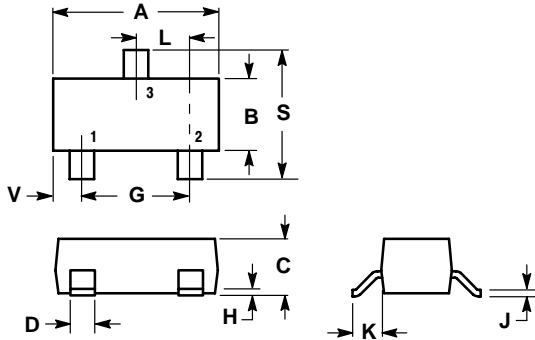
A common means of protecting high-speed data lines is to employ low-capacitance diode arrays in a rail-to-rail configuration. Two devices per line are connected between two fixed voltage references such as V_{CC} and ground. When the transient voltage exceeds the forward voltage (V_F) drop of the diode plus the reference voltage, the diodes direct the

surge to the supply rail or ground. This method has several advantages including low loading capacitance, fast response time, and inherent bidirectionality (within the reference voltages). See Figure 1 for the test circuit used to verify the ESD rating for this device.

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PACKAGE DIMENSIONS

SOT-23 (TO-236)
CASE 318-08
ISSUE AK

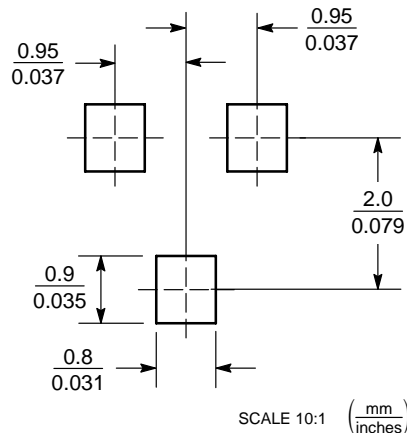


- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
 4. 318-01 THRU -07 AND -09 OBSOLETE, NEW STANDARD 318-08.

| DIM | INCHES | | MILLIMETERS | |
|-----|--------|--------|-------------|-------|
| | MIN | MAX | MIN | MAX |
| A | 0.1102 | 0.1197 | 2.80 | 3.04 |
| B | 0.0472 | 0.0551 | 1.20 | 1.40 |
| C | 0.0350 | 0.0440 | 0.89 | 1.11 |
| D | 0.0150 | 0.0200 | 0.37 | 0.50 |
| G | 0.0701 | 0.0807 | 1.78 | 2.04 |
| H | 0.0005 | 0.0040 | 0.013 | 0.100 |
| J | 0.0034 | 0.0070 | 0.085 | 0.177 |
| K | 0.0140 | 0.0285 | 0.35 | 0.69 |
| L | 0.0350 | 0.0401 | 0.89 | 1.02 |
| S | 0.0830 | 0.1039 | 2.10 | 2.64 |
| V | 0.0177 | 0.0236 | 0.45 | 0.60 |

- STYLE 11:
PIN 1. ANODE
2. CATHODE
3. CATHODE-ANODE

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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